

HTN036N03P DFN5x6 TN036N03P

Absolute Maximum Ratings at $T_J=25^\circ\text{C}$ (unless otherwise specified)

Parameter	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	$T_C=25^\circ\text{C}$	70	A
	$T_C=100^\circ\text{C}$	64	
Drain to Source Voltage	V_{DS}	30	V
		± 20	V
Pulsed Drain Current		70	A
		54	mJ
		50	W
		-55 to 150	$^\circ\text{C}$

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Case	R_{JC}	2.5	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction-Ambient	R_{JA}	50	$^\circ\text{C}/\text{W}$

Electrical Characteristics					
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS}=0V, V_{DS}=24V, T_j=25^\circ C$	-		
	$R_{DS(on)}$		-	3	3.6
Transconductance	g_{fs}		4.2		
Gate Resistance	R_G	$V_{GS}=0V, V_{DS} \text{ Open}, f=1\text{MHz}$	-	25.2	-
			-	2.0	S
Dynamic Characteristics					
Input Capacitance	C_{iss}		-	2015	
		$V_{GS}=0V, V_{DS}=15V, f=1\text{MHz}$	-	365	-
Reverse Transfer Capacitance	C_{rss}		-	205	pF
Total Gate Charge (10V)	$Q_g(10V)$		-	42	
	$Q_g(4.5V)$		-	21	
	Q_{gs}	$V_{DD}=15V, I_D=18A, V_{GS}=10V$	-	6	nC
	Q_{gd}		-	9	
Turn on Delay Time	$t_{d(on)}$		-	15	
Rise time	t_r		-	20	
Turn off Delay Time	$t_{d(off)}$	$V_{DD}=15V, I_D=1A, V_{GS}=10V, R_G=6\Omega$	-	72	ns
Fall Time	t_f		-	20	
Reverse Diode Characteristics					
	V_{SD}	$V_{GS}=0V, I_F=15A$	-	0.7	1.1
Reverse Recovery Charge	Q_{rr}	$I_F=15A, dI_F/dt=100A/\mu s$	-	15.0	-
			-	8.0	nC

Fig 1. Typical Output Characteristics

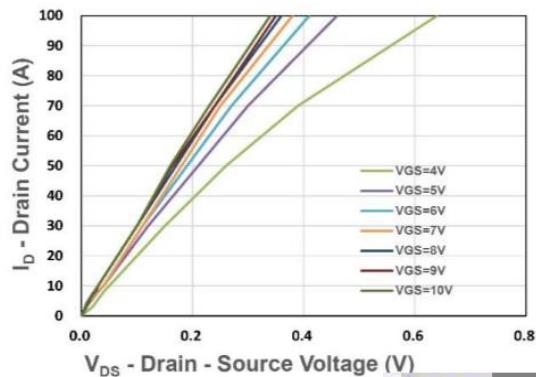


Figure 2. On-Resistance vs. Gate-Source Voltage

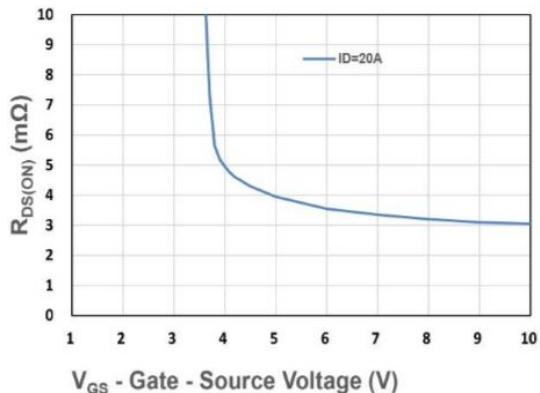


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

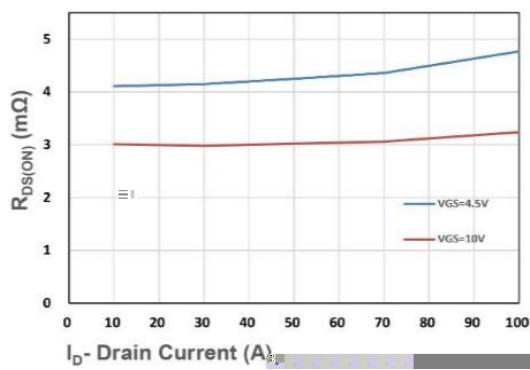


Figure 4. Normalized On-Resistance vs. Junction Temperature

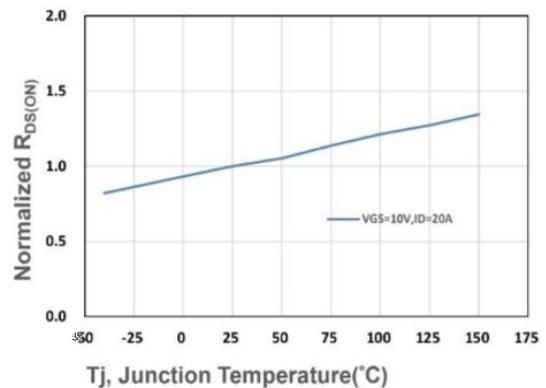


Figure 5. Normalized Threshold Voltage VS Junction Temperature

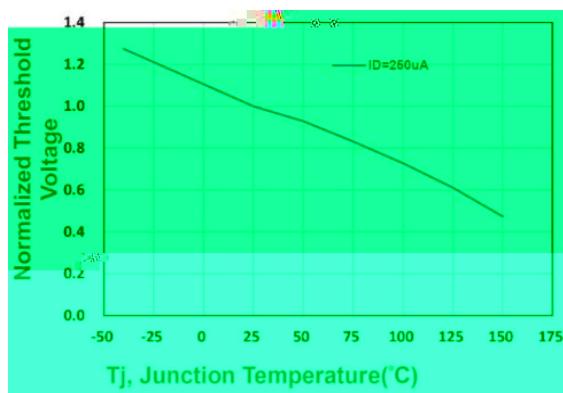


Figure 6. Typical Source-Drain Diode Forward Voltage

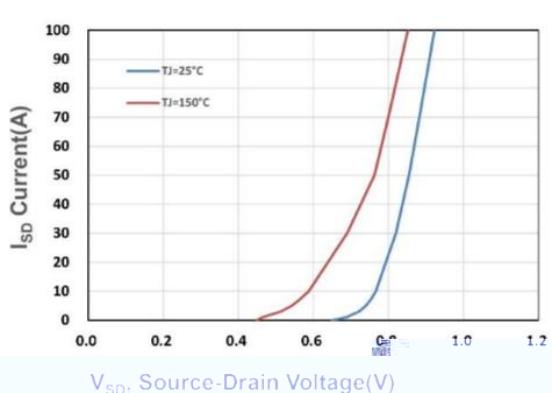


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

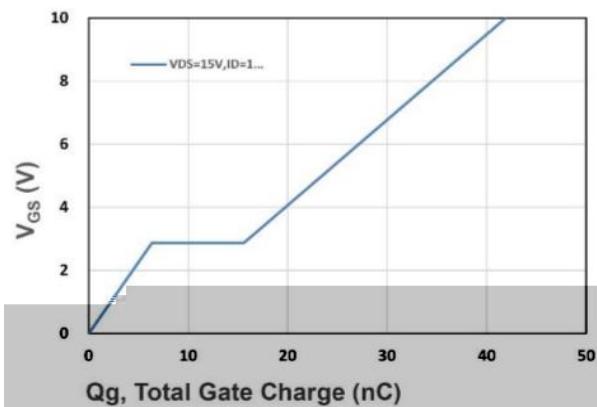


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

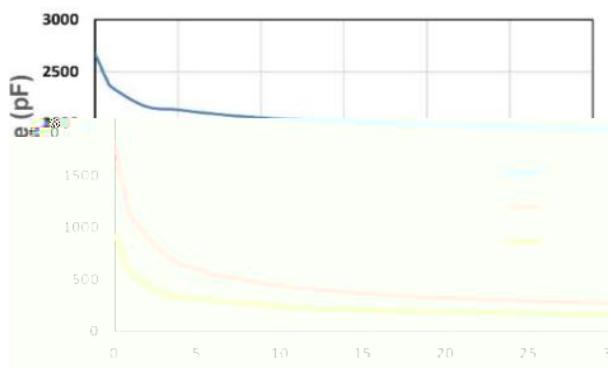


Figure 9. Maximum Safe Operating Area

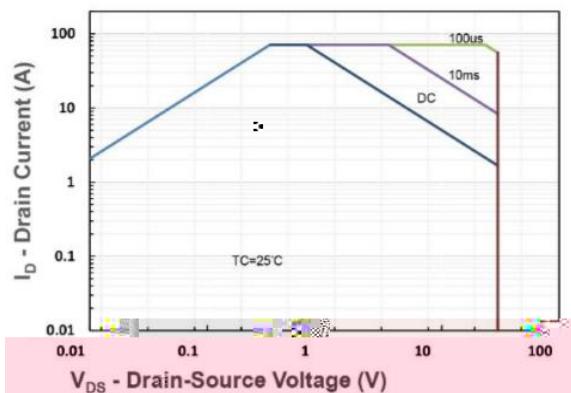


Figure 10. Maximum Drain Current vs. Case Temperature

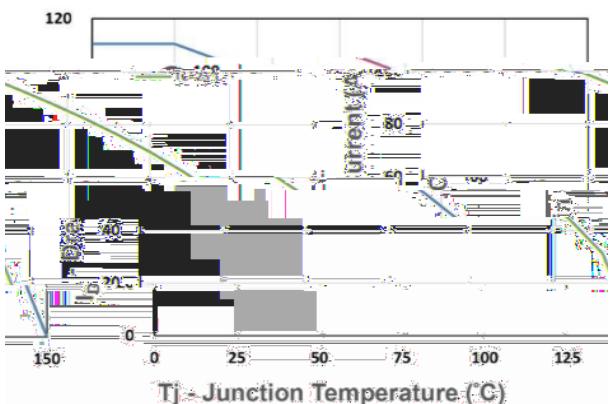


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case

